

# SGM4551B Dual Bidirectional I<sup>2</sup>C Bus and SMBus Voltage-Level Translator

## **GENERAL DESCRIPTION**

The SGM4551B is a 2-bit, SMBus, dual, bidirectional,  $I^2C$  voltage translator with the ability of enable (EN) function. For  $V_{REF1}$ , the typical operation range is from 1.2V to 3.3V and the typical operation for  $V_{REF2}$  is from 1.8V to 5V.

The signal can be transmitted bilaterally from 1.2V to 5V. The propagation delay is significant small as the low on-resistance of SGM4551B. Also, if the EN pin is in high position, the voltage translator is transparent and then it allows the connection between SCL1 and SCL2, SDA1 and SDA2 respectively. In addition, in this state, the transmitting direction is bidirectional. However, the transmitting will be suspended if the EN pin is in low state as the high-impedance property at this moment.

For the applications, the connections of the devices and bus length are limited as the 400pF capacitance of the bus pin. However, SGM4551B allows the isolation between two sides of  $I^2C$  bus so that more and more  $I^2C$  devices can be added and connected with SGM4551B.

Two different kinds of bus frequencies are supported by SGM4551B, one is 400kHz and the other is 100kHz. Also, if two frequencies for the buses are required, the priority of 400kHz should be always higher than that of 100kHz. Because of the adding of the additional delay, the operational frequency of the device must be lower than 400kHz if the frequency of the master is equal to 400kHz.

For the application of standard I<sup>2</sup>C, the pull-up resistor is required for the logic high levels, which means that the operation for I<sup>2</sup>C in this case is open-drain. Each side of the repeater requires a pull-up resistor and the value of resistor depends on the operation of SGM4551B. Also, when multiple masters are connected with SGM4551B, the standard operation current is 3mA, and high current can be taken into account under the specific conditions.

The resistance between SDA1 and SDA2 is low when the state of them is low. However, if the state of SDA1 or SDA2 is high, the level of high position depends on the corresponding voltage reference. In the transparent mode, when the position of SDA1 is high, SDA2 must be pulled to a high level through the pull-up resistor. In addition, the transition for high and low voltage is seamless which can be selected by the users.

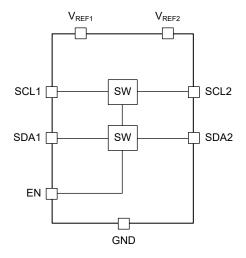
Because of the same electrical characteristics for all the outputs of SGM4551B, so that the deviations of the propagation delay and voltage is extremely small. In addition, this advantage is good for the transition of discrete transistors as the symmetrical switch inside SGM4551B. On top of this, SGM4551B can also provide the protection of ESD for the devices with weak ESD ability.

The SGM4551B is available in Green SOT-23-8 and VSSOP-8 packages. It operates over an ambient temperature range of -40°C to +85°C.

## **FEATURES**

- Bidirectional I<sup>2</sup>C Translator
- Support I<sup>2</sup>C and SMBus Compatible
- Propagation Delay: Less than 5.5ns
- Acceptable Voltage Reference
  - 1.2V V<sub>REF1</sub> and 1.8V, 2.5V, 3.3V, or 5V V<sub>REF2</sub>
  - 1.8V V<sub>REF1</sub> and 2.5V, 3.3V, or 5V V<sub>REF2</sub>
  - 2.5V V<sub>REF1</sub> and 3.3V or 5V V<sub>REF2</sub>
  - 3.3V V<sub>REF1</sub> and 5V V<sub>REF2</sub>
- Low On-Resistance: 3.5Ω (TYP)
- GPIO Ports with I<sup>2</sup>C Open-Drain Logic (SCL1, SDA1, SCL2 and SDA2)
- Mixed-Mode Signal be Supported by I/O Ports with 5V Tolerant
- When EN is Low, SGM4551B is in High-Impedance Mode
- Lock-Up-Free Operation for Isolation when EN = Low
- The Pinout of the Internal Material is Beneficial for PCB Layout
- Available in Green SOT-23-8 and VSSOP-8 Packages

## LOGIC DIAGRAM



## **FUNCTION TABLE**

EN <sup>(1)</sup>	FUNCTION				
Н	SCL1 = SCL2, SDA1 = SDA2.				
L	Disconnect.				

#### NOTE:

1. The transparent mode will be launched if the voltage of EN pin is 1V higher than the voltage of SCL1 and SCL2. And so does the condition of SDA. H = HIGH level, L = LOW level.

## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	TEMPERATURE ORDERING NUMBER		PACKING OPTION
COMAEE AD	SOT-23-8	-40°C to +85°C	SGM4551BYN8G/TR	SZ6XX	Tape and Reel, 3000
SGM4551B	VSSOP-8	-40°C to +85°C	SGM4551BYVS8G/TR	1J6 XXXX	Tape and Reel, 3000

#### MARKING INFORMATION

NOTE: XX = Date Code. XXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

#### **ABSOLUTE MAXIMUM RATINGS**

DC Reference Voltage Range	
V <sub>REF1</sub>	0.3V to 6V
V <sub>REF2</sub>	0.3V to 6V
Input Voltage Range (1), V <sub>1</sub>	0.3V to 6V
Input/Output Voltage Range (1), V <sub>I/O</sub>	0.3V to 6V
Continuous Channel Current	64mA
Input Clamp Current, I <sub>IK</sub> (V <sub>I</sub> < 0)	50mA
Package Thermal Resistance	
SOT-23-8, θ <sub>JA</sub>	198.3°C/W
SOT-23-8, θ <sub>JB</sub>	102.6°C/W
SOT-23-8, θ <sub>JC</sub>	157°C/W
VSSOP-8, θ <sub>JA</sub>	189°C/W
VSSOP-8, θ <sub>JB</sub>	123°C/W
VSSOP-8, $\theta_{JC}$	56.5°C/W
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility (2) (3)	
HBM	±3000V
CDM	±1000V

#### NOTES:

- 1. When the input and output current ratings are observed, the input and I/O negative voltage ratings may be exceeded.
- 2. For human body model (HBM), all pins comply with ANSI/ESDA/JEDEC JS-001 specifications.
- 3. For charged device model (CDM), all pins comply with ANSI/ESDA/JEDEC JS-002 specifications.

## RECOMMENDED OPERATING CONDITIONS

Operating Temperature Range.....-40°C to +85°C

### **OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

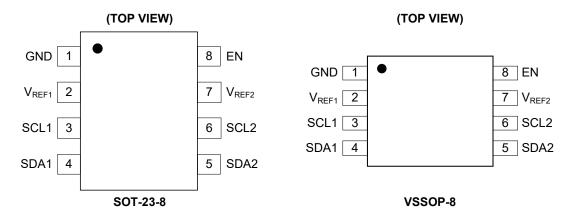
## **ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

#### **DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

# **PIN CONFIGURATIONS**



# **PIN DESCRIPTION**

P	IN	NAME	FUNCTION
SOT-23-8	VSSOP-8	NAIVIE	FUNCTION
1	1	GND	Ground.
2	2	V <sub>REF1</sub>	Low-side Reference Supply Voltage for SCL1 and SDA1.
3	3	SCL1	Low-side Clock Signal.
4	4	SDA1	Low-side Data Signal.
5	5	SDA2	High-side Data Signal.
6	6	SCL2	High-side Clock Signal.
7	7	$V_{REF2}$	High-side Reference Supply Voltage for SCL2 and SDA2.
8	8	EN	Enable Control Pin.

# **ELECTRICAL CHARACTERISTICS**

 $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ typical values are at } T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

PARAMETER		SYMBOL	CONDITI	ONS	MIN	TYP	MAX	UNITS
Input/Output Voltage		V <sub>I/O</sub>	SCL1, SDA1, SCL2, SDA2		0		5	V
Reference Voltage		$V_{REF1}$			0		5	V
Reference Voltage		$V_{REF2}$			0		5	V
Enable Input Voltage		$V_{EN}$			0		5	V
Pass Switch Current		I <sub>PASS</sub>					64	mA
Input Clamp Voltage		V <sub>IK</sub>	I <sub>I</sub> = -18mA, V <sub>EN</sub> = 0V				-1.2	V
Input Leakage Curre	nt	I <sub>IH</sub>	V <sub>I</sub> = 5V, V <sub>EN</sub> = 0V				8	μA
Enable Leakage Cur	rent	I <sub>EN</sub>	V <sub>I</sub> = 5V				1	μA
Input Capacitance		C <sub>I(EN)</sub>	V <sub>i</sub> = 3V or 0V			15		pF
Off Capacitance	SCLn, SDAn	C <sub>IO(OFF)</sub>	$V_{O} = 3V \text{ or } 0V, V_{EN} = 0$	V		8		pF
On Capacitance	SCLn, SDAn	C <sub>IO(ON)</sub>	$V_{\rm O} = 3V \text{ or } 0V, V_{\rm EN} = 3$	V		7		pF
				V <sub>EN</sub> = 4.5V		3.5	5.5	
			)/ 0)/ l 04*** A	V <sub>EN</sub> = 3.0V		3.8	6.0	
			$V_1 = 0V, I_0 = 64mA$	V <sub>EN</sub> = 2.3V		4.0	6.0	Ω
On-Resistance (1)	SCLn, SDAn	Ron		V <sub>EN</sub> = 1.5V		4.5	6.5	
			V 0.4V L 45A	V <sub>EN</sub> = 4.5V	1.5	4.5	7.0	
			$V_1 = 2.4V, I_0 = 15mA$	V <sub>EN</sub> = 3.0V	11	40	65	
			V <sub>I</sub> = 1.7V, I <sub>O</sub> = 15mA	V <sub>EN</sub> = 2.3V	9	35	58	

### NOTE:

1. It is measured by a voltage drop between SCL1 and SCL2, or between SDA1 and SDA2, at the indicated current through the switch. The on-resistance depends on the lowest voltage of the two ports.

# **SWITCHING CHARACTERISTICS**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> = 50pF	C <sub>L</sub> = 30pF	C <sub>L</sub> = 15pF	UNITS
AC Performance (Tr	anslating Down) (2)					
(Typical values are at	$T_A = +25^{\circ}C$ , EN = 3.3	$V, V_{IH} = 2.3V, V_{IL} = 0$	$V, V_M = 1.15V, unless$	otherwise noted.) (Se	ee Figure 1)	
t <sub>PLH</sub>	SCL2 or SDA2	SCL1 or SDA1	1.0	0.7	0.5	ne
t <sub>PHL</sub>	SCLZ OF SDAZ	SCLT OF SDAT	1.1	0.7	0.5	ns
AC Performance (Tr	anslating Down) (2)					
(Typical values are at	$T_A = +25^{\circ}C$ , EN = 2.5	$V, V_{IH} = 1.5V, V_{IL} = 0$	$V$ , $V_M$ = 0.75 $V$ , unless	otherwise noted.) (Se	ee Figure 1)	
t <sub>PLH</sub>	SCL2 or SDA2	2 SCL1 or SDA1	1.1	0.7	0.5	no
t <sub>PHL</sub>	SCLZ OF SDAZ		1.1	0.7	0.5	ns
AC Performance (Tr	anslating Up) (3)					
(Typical values are at	$T_A = +25^{\circ}C$ , EN = 3.3	$V, V_{IH} = 2.3V, V_{IL} = 0$	$V, V_T = 3.3V, V_M = 1.1$	5V, $R_L$ = 300Ω, unless	s otherwise noted.) (S	See Figure 1)
t <sub>PLH</sub>	SCL1 or SDA1	SCL2 or SDA2	1.6	1.0	0.7	20
t <sub>PHL</sub>	SCLI OI SDAT	SCLZ OF SDAZ	1.2	0.8	0.6	ns
AC Performance (Tr	anslating Up) <sup>(3)</sup>					
(Typical values are at	$T_A = +25^{\circ}C$ , EN = 2.5	$V, V_{IH} = 1.5V, V_{IL} = 0$	$V, V_T = 2.5V, V_M = 0.7$	$^{5}$ V, R <sub>L</sub> = $300\Omega$ , unless	s otherwise noted.) (	See Figure 1)
t <sub>PLH</sub>	SCL1 or SDA1	SCL2 or SDA2	1.6	1.0	0.7	no
t <sub>PHL</sub>	SOLT OF SDAT	SCLZ OF SDAZ	1.2	0.8	0.6	ns

### NOTES:

- 2. TRANSLATING DOWN: The high voltage side drives the low voltage side.
- 3. TRANSLATING UP: The low voltage side drives the high voltage side.



# **WAVEFORMS**

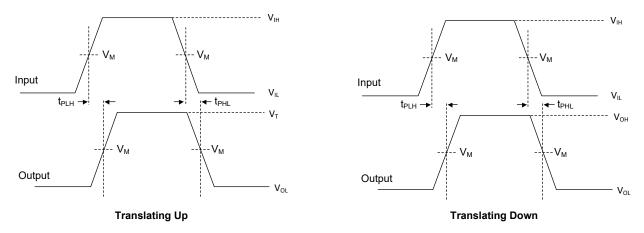
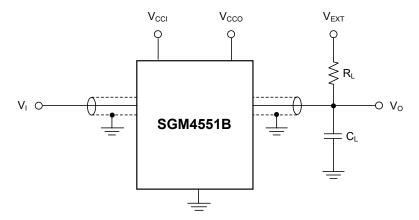


Figure 1. Translating Up and Translating Down Waveforms

# **TEST CIRCUIT**



Definitions for test circuit:

 $R_L$  = Load resistance.

 $C_L$  = Load capacitance including jig and probe capacitance.

V<sub>EXT</sub> = External voltage for measuring switching times.

 $V_{CCI}$  = Supply voltage associated with the input.

 $V_{\text{CCO}}$  = Supply voltage associated with the output.

Figure 2. Test Circuit for Measuring Switching Times

## APPLICATION INFORMATION

# General Applications of I<sup>2</sup>C

Since the limitation of the load capacitance is 400pF, so that the number of devices which are connected to SGM4551B will be limited. Also, the advantage of SGM4551B is that it can isolate the buses of two sides, which means that more and more I<sup>2</sup>C devices can be connected with this device.

Two different kinds of bus frequencies are supported by SGM4551B, one is 400kHz and the other is 100kHz. Also, if two frequencies for the buses are required, the priority of 400kHz should be always higher than that of 100kHz. Because of the adding of the additional delay of the repeater,

the operational frequency of the device must be lower than 400kHz if the frequency of the master is equal to 400kHz.

For the application of standard I<sup>2</sup>C, the pull-up resistor is required for the logic high levels, which means that the operation for I<sup>2</sup>C in this case is open-drain. Each side of the repeater requires a pull-up resistor and the value of resistors depend on the operation of SGM4551B. Also, when multiple masters are connected with SGM4551B, the standard operation current is 3mA, and high current can be taken into account under the specific conditions.

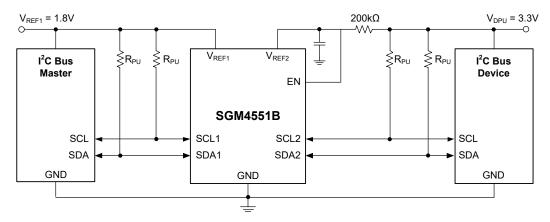


Figure 3. Typical Application Circuit (Switch Always Enabled)

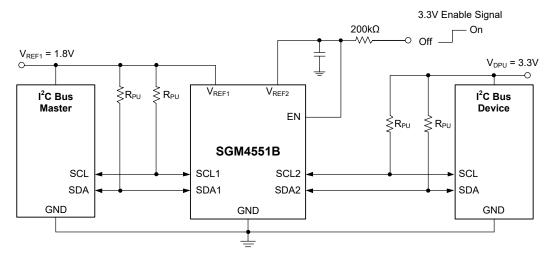


Figure 4. Typical Application Circuit (Switch Enable Control)

# **APPLICATION INFORMATION (continued)**

## **Bidirectional Translation**

For both directional applications, it is recommended to connect reference pins to  $V_{REF2}$ . Also, both SCL and SDA pins should be pulled up by a resistor. A bypass capacitor should be added at the pin of  $V_{REF2}$  to improve the stability. Both the outputs of master and slave device can be push-pull or open-drain (a pull-up resistor is required at this case). In addition, if the users desire to use push-pull structure to generate the output, SGM4551B can operate unidirectional or be controlled by direction-control mechanism to prevent the risk of contentions. For open-drain output structure, it does not need any control mechanism for the transmitting direction.

The pin of  $V_{\text{REF1}}$  should be tied to the  $V_{\text{CC}}$  of processor directly.

## Sizing Pull-Up Resistor

The function of pull-up resistor is used to limit the operation current to 15mA when the output is in high position, which means that the pass voltage will be around 350mV. The larger the current flowing to the pull-up resistor, the larger the pass voltage it is. To meet the requirement of 15mA, the pull-up resistor should be calculated as below:

$$R_{PU} = \frac{V_{DPU} - 0.35V}{0.015A}$$

Table 2 illustrates the corresponding value of pull-up resistor for different  $V_{REF}$  and operation current. The +10% resistance value is recommended, as it ensures the pass voltage within 350mV. In addition, if considering use a driver, please make sure that it has the ability to sink the total current of SGM4551B.

Table 1. Application Operating Conditions (1)

table in the induction of the induction							
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS		
Reference Voltage	$V_{REF2}$	V <sub>REF1</sub> + 0.6	V <sub>REF1</sub> + 0.6	V <sub>REF1</sub> + 0.6	V		
Enable Input Voltage	$V_{EN}$	V <sub>REF1</sub> + 0.6	V <sub>REF1</sub> + 0.6	V <sub>REF1</sub> + 0.6	V		
Reference Voltage	$V_{REF1}$	0	1.5	4.4	٧		
Pass Switch Current	I <sub>PASS</sub>		15		mA		
Reference Transistor Current	I <sub>REF</sub>		5		μΑ		
Operating Temperature Range	T <sub>A</sub>	-40		85	$^{\circ}$ C		

#### NOTE:

1. The typical values are measured at  $T_A = +25$ °C.

Table 2. Pull-Up Resistor Values (1) (2)

	Pull-Up Resistor Value (Ω)								
$V_{DPU}$	15	mA	10	mA	3mA				
	NOMINAL	+10% (3)	NOMINAL +10% (3)		NOMINAL	+10% <sup>(3)</sup>			
5V	310	341	465	512	1550	1705			
3.3V	197	217	295	325	983	1082			
2.5V	143	158	215	237	717	788			
1.8V	97	106	145	160	483	532			
1.5V	77	85	115	127	383	422			
1.2V	57	63	85	94	283	312			

#### NOTES:

- 1. Measured at the condition of  $V_{OL}$  = 350mV.
- 2. The V<sub>OL</sub> of the output is equal to 175mV.
- 3. 10% range of resistor for suitable operation current.

# **APPLICATION INFORMATION (continued)**

#### SGM4551B Bandwidth

Different kinds of applications support different frequencies. Also, SGM4551B can operate for the conditions which the frequency is greater than 50MHz. The loading of the SGM4551B affects the maximum operation frequency. Also, the bandwidth of the SGM4551B is affected by the on-resistance and on-capacitance.

The corner frequency (-3dB point) of SGM4551B is 250MHz, which is measured in an analog way. However, for digital applications, the previous five harmonics of the input signal should never be degraded by the device, which means that the maximum bandwidth should be five times larger than the input digital signal. Also, the previous five harmonics are significant. Since the corner frequency of SGM4551B is around 250MHz, so that this device can support the digital signal with the frequency of 50MHz.

There is no drive capability for SGM4551B so that the driver of the host should be strengthen enough for the condition of high frequency. If the output structure of the host device is push-pull, the pull-up resistor will not be taken into account, which can significantly decrease the length of trace.

The maximum frequency harmonic (knee frequency: f<sub>knee</sub>) can be calculated by the following equations. For the input signal with fast rising or falling edge, like square waveform, the high frequency component is infinite. However, the knee frequency

is used to determine the important frequency component, which means that if the frequency of harmonics is larger than this limitation, the users can assume that it will not influence the shape of the input signal.

The equations to calculate f<sub>knee</sub> are shown as below:

 $f_{knee} = 0.5/RT(10\% - 90\%)$  $f_{knee} = 0.4/RT(20\% - 80\%)$ 

If the threshold of the input signal is determined by 10% to 90%, the knee frequency can be defined as 0.5 divided by the rising time. If the threshold of the input signal is determined by 20% to 80%, the knee frequency can be defined as 0.4 divided by the rising time.

The following suggestions should be accepted to improve the performance of SGM4551B:

- 1. Minimize the distance between processor and SGM4551B as close as possible by minimizing the length of trace in PCB.
- 2. The ringing and reflection can be improved by reducing the length of trace which is less than half the transmission time of the signal.
- 3. A pull-up resistor should be taken into account to be added at 1.8V side for reducing the overshoot. Also, a falling edge with slow falling time is expected by the application of SGM4551B.

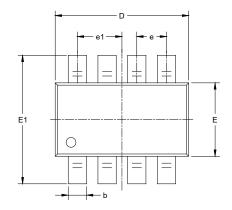
## **REVISION HISTORY**

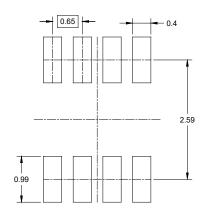
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

NOVEMBER 2025 – REV.A.1 to REV.A.2	Page
Updated General Description section	1
JANUARY 2025 – REV.A to REV.A.1	Page
Added VSSOP-8 Package	All
Updated Absolute Maximum Ratings section	3
Updated Switching Characteristics section	
Updated Application Information section	9
Changes from Original to REV.A (FEBRUARY 2015)	Page
Changed from product preview to production data	All

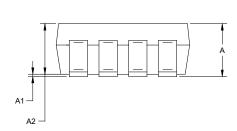


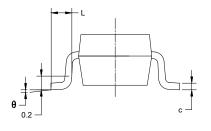
# **PACKAGE OUTLINE DIMENSIONS SOT-23-8**





RECOMMENDED LAND PATTERN (Unit: mm)



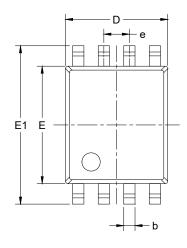


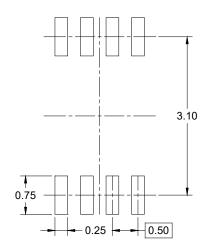
Symbol	_	nsions meters	Dimensions In Inches			
	MIN	MAX	MIN	MAX		
Α	1.050	1.250	0.041	0.049		
A1	0.000	0.100	0.000	0.004		
A2	1.050	1.150	0.041	0.045		
b	0.300	0.500	0.012	0.020		
С	0.100	0.200	0.004	0.008		
D	2.820	3.020	0.111	0.119		
E	1.500	1.700	0.059	0.067		
E1	2.650	2.950	0.104	0.116		
е	0.650	BSC	0.026 BSC			
e1	0.975 BSC		0.038 BSC			
L	0.300	0.600	0.012	0.024		
θ	0°	8°	0°	8°		

## NOTES:

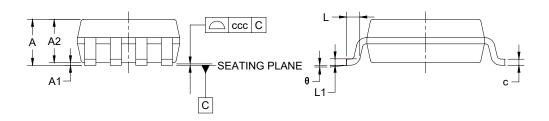
- Body dimensions do not include mode flash or protrusion.
  This drawing is subject to change without notice.

# PACKAGE OUTLINE DIMENSIONS VSSOP-8





## RECOMMENDED LAND PATTERN (Unit: mm)



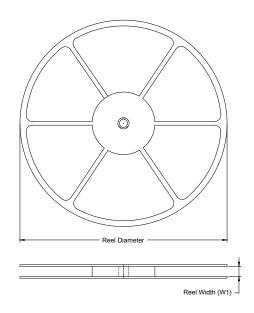
Cymhal	Dimensions In Millimeters							
Symbol	MIN	NOM	MAX					
А	-	-	1.000					
A1	0.000	-	0.150					
A2	0.600		0.850					
b	0.170	0.170 -						
С	0.080	0.080						
D	1.900	-	2.100					
Е	2.200	-	2.400					
E1	3.000	-	3.200					
е		0.500 BSC						
L	0.150	-	0.400					
L1	0.120 BSC							
θ	0°	-	8°					
ccc	0.100							

#### **NOTES**

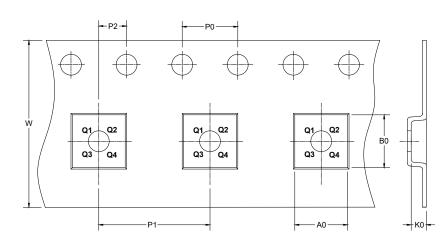
- 1. This drawing is subject to change without notice.
- 2. The dimensions do not include mold flashes, protrusions or gate burrs.
- 3. Reference JEDEC MO-187 CA.

# TAPE AND REEL INFORMATION

## **REEL DIMENSIONS**



# **TAPE DIMENSIONS**



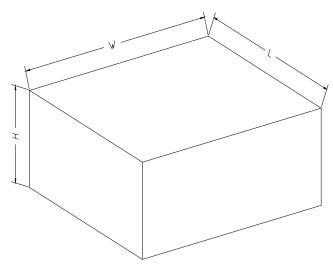
DIRECTION OF FEED

NOTE: The picture is only for reference. Please make the object as the standard.

# **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT-23-8	7"	9.5	3.23	3.17	1.37	4.0	4.0	2.0	8.0	Q3
VSSOP-8	7"	9.5	2.25	3.35	1.05	4.0	4.0	2.0	8.0	Q3

# **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

# **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18